

SMITH CHART EXAMPLES

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Smith Chart for the Impedance Plot

It will be easier if we normalize the load impedance to the characteristic impedance of the transmission line attached to the load.

$$z = \frac{Z}{Z_0} = r + jx$$

$$z = \frac{1 + \Gamma}{1 - \Gamma}$$

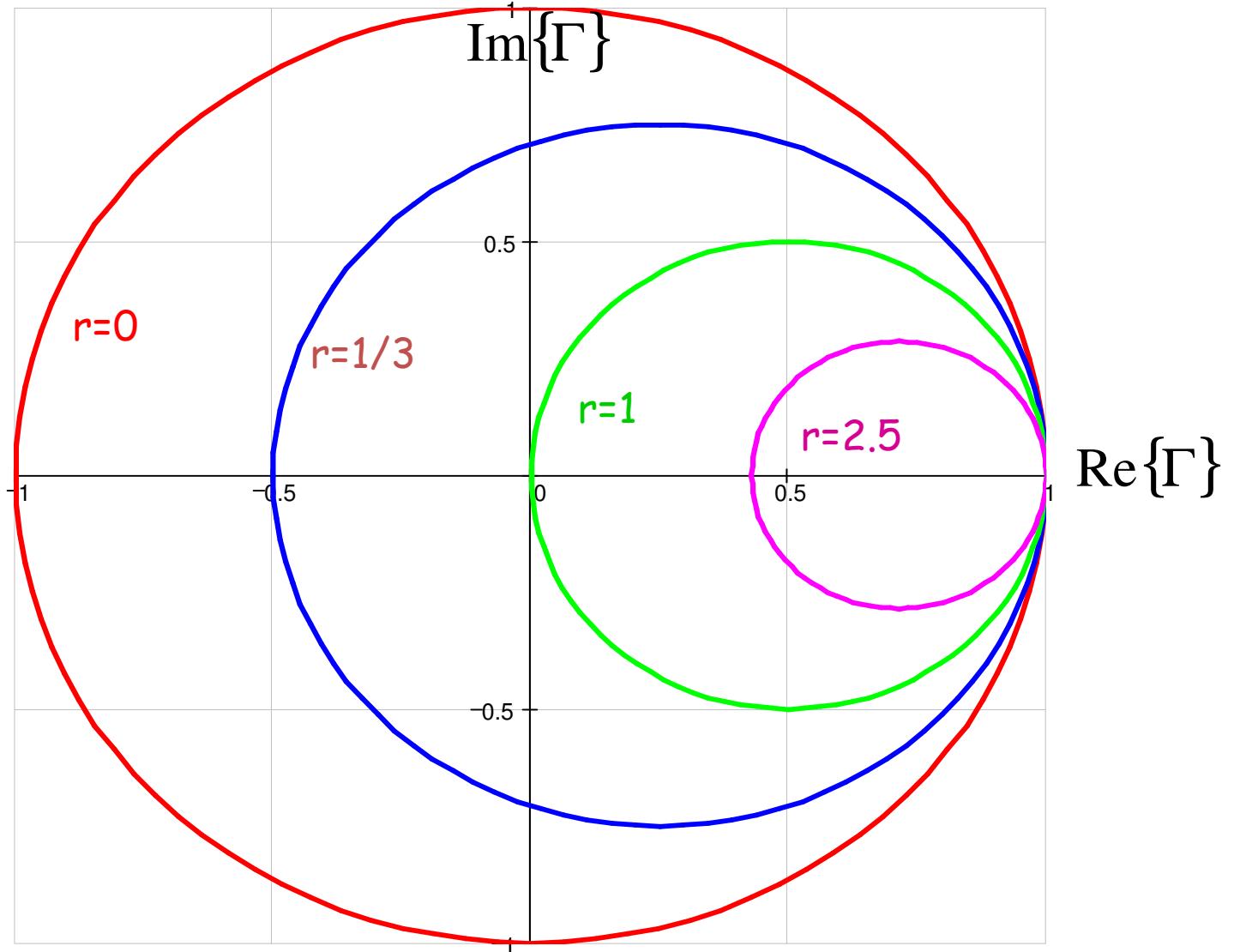
Since the impedance is a complex number, the reflection coefficient will be a complex number

$$\Gamma = u + jv$$

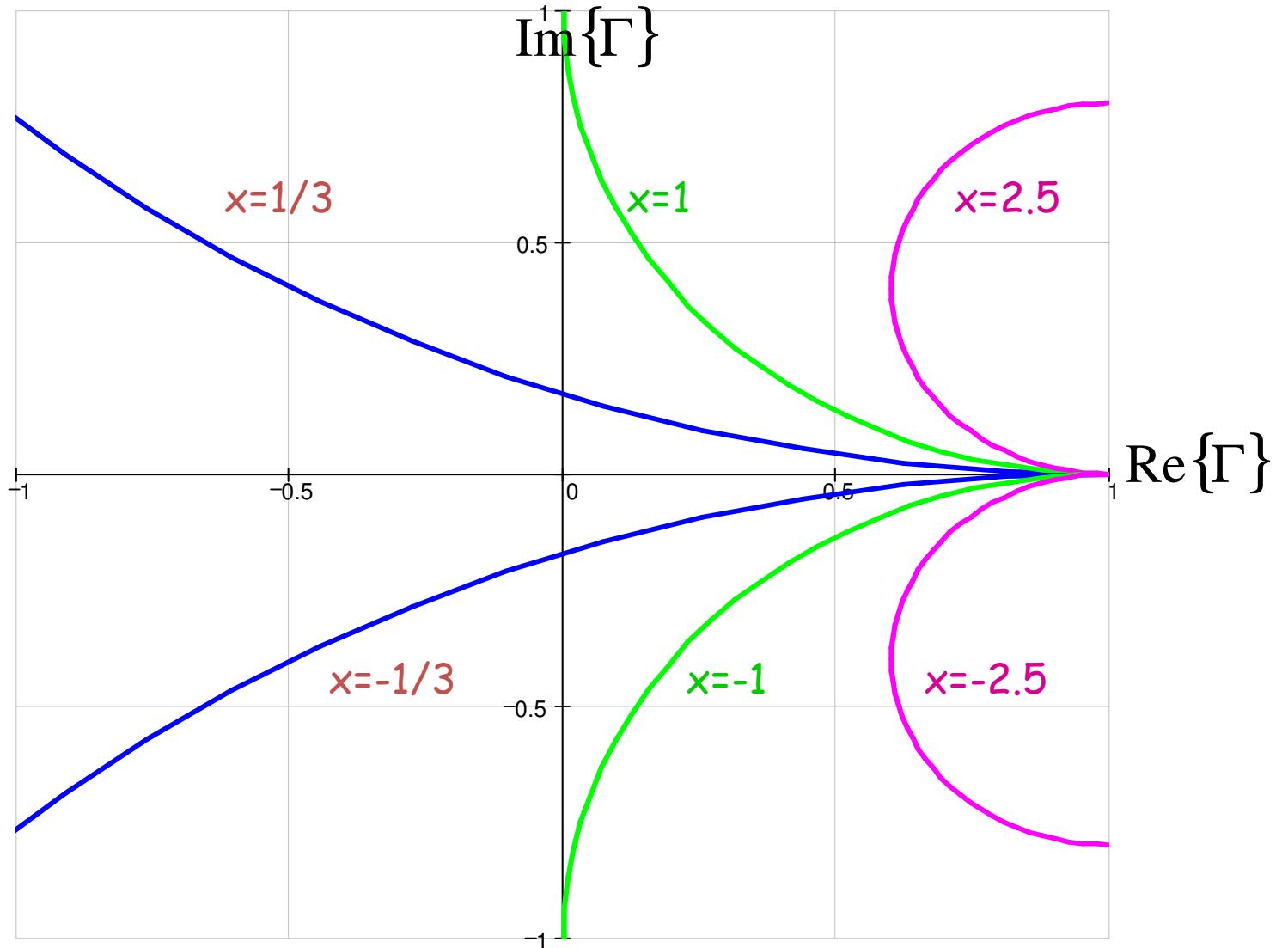
$$r = \frac{1 - u^2 - v^2}{(1 - u)^2 + v^2}$$

$$x = \frac{2v}{(1 - u)^2 + v^2}$$

Real Circles

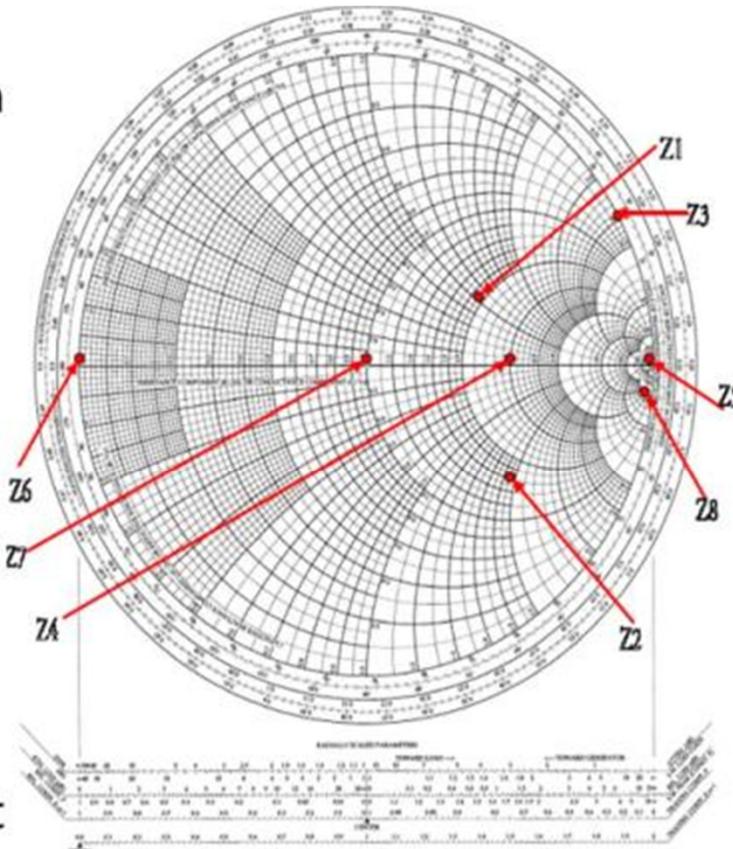


Imaginary Circles



- Impedance divided by lin impedance (50 Ohms)

- $Z_1 = 100 + j50$
- $Z_2 = 75 - j100$
- $Z_3 = j200$
- $Z_4 = 150$
- $Z_5 = \text{infinity}$ (an open circuit)
- $Z_6 = 0$ (a short circuit)
- $Z_7 = 50$
- $Z_8 = 184 - j900$



- Then, normalize and plot
The points are plotted as follows:

- $z_1 = 2 + j$
- $z_2 = 1.5 - j2$
- $z_3 = j4$
- $z_4 = 3$
- $z_5 = \text{infinity}$
- $z_6 = 0$
- $z_7 = 1$
- $z_8 = 3.68 - j18S$

Normalized Admittance

$$y = \frac{Y}{Y_o} = YZ_o = g + jb$$

$$y = \frac{1 - \Gamma}{1 + \Gamma}$$

$$g = \frac{1 - u^2 - v^2}{(1 + u)^2 + v^2}$$

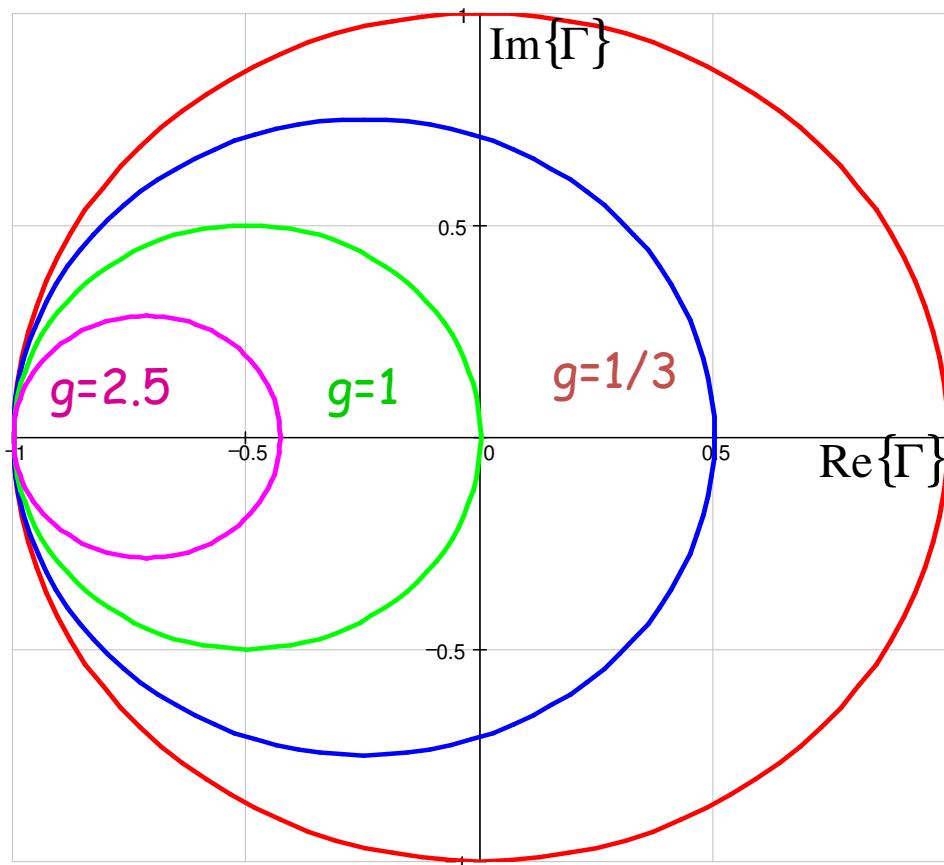

$$\left(u + \frac{g}{1+g}\right)^2 + v^2 = \frac{1}{(1+g)^2}$$

$$b = \frac{-2v}{(1 + u)^2 + v^2}$$

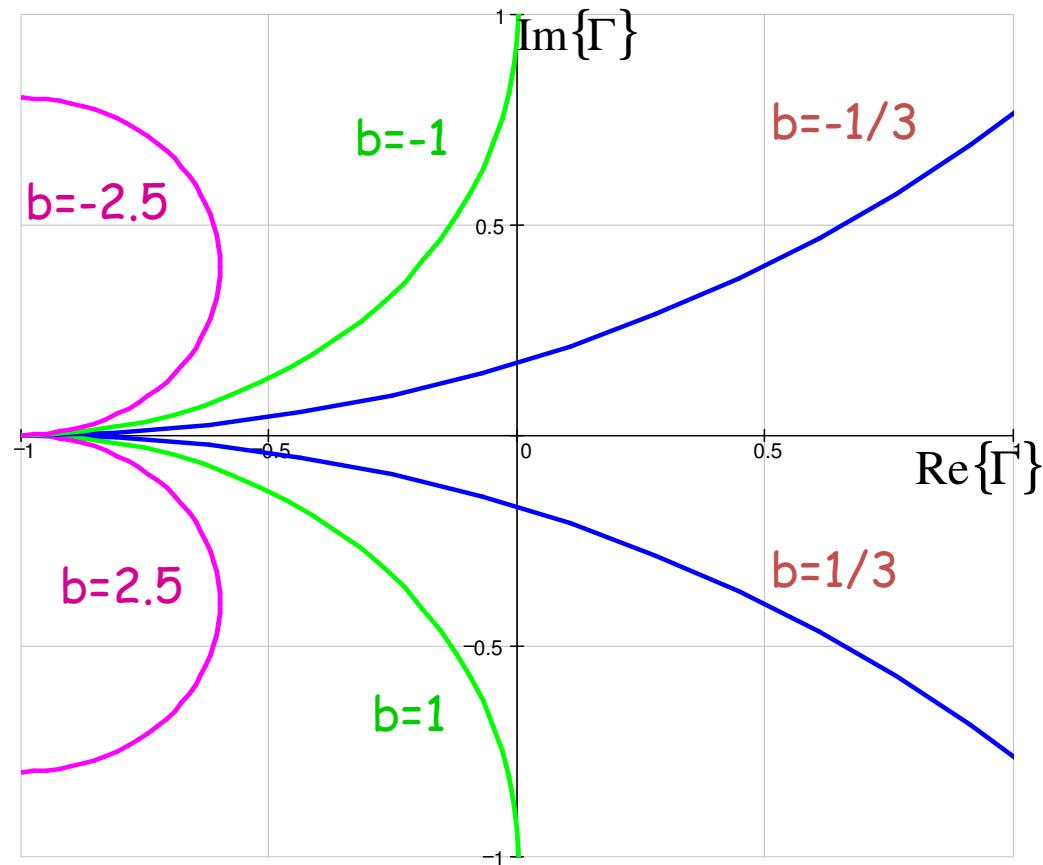

$$(u + 1)^2 + \left(v + \frac{1}{b}\right)^2 = \frac{1}{b^2}$$

These are equations for circles on the (u,v) plane

Real admittance

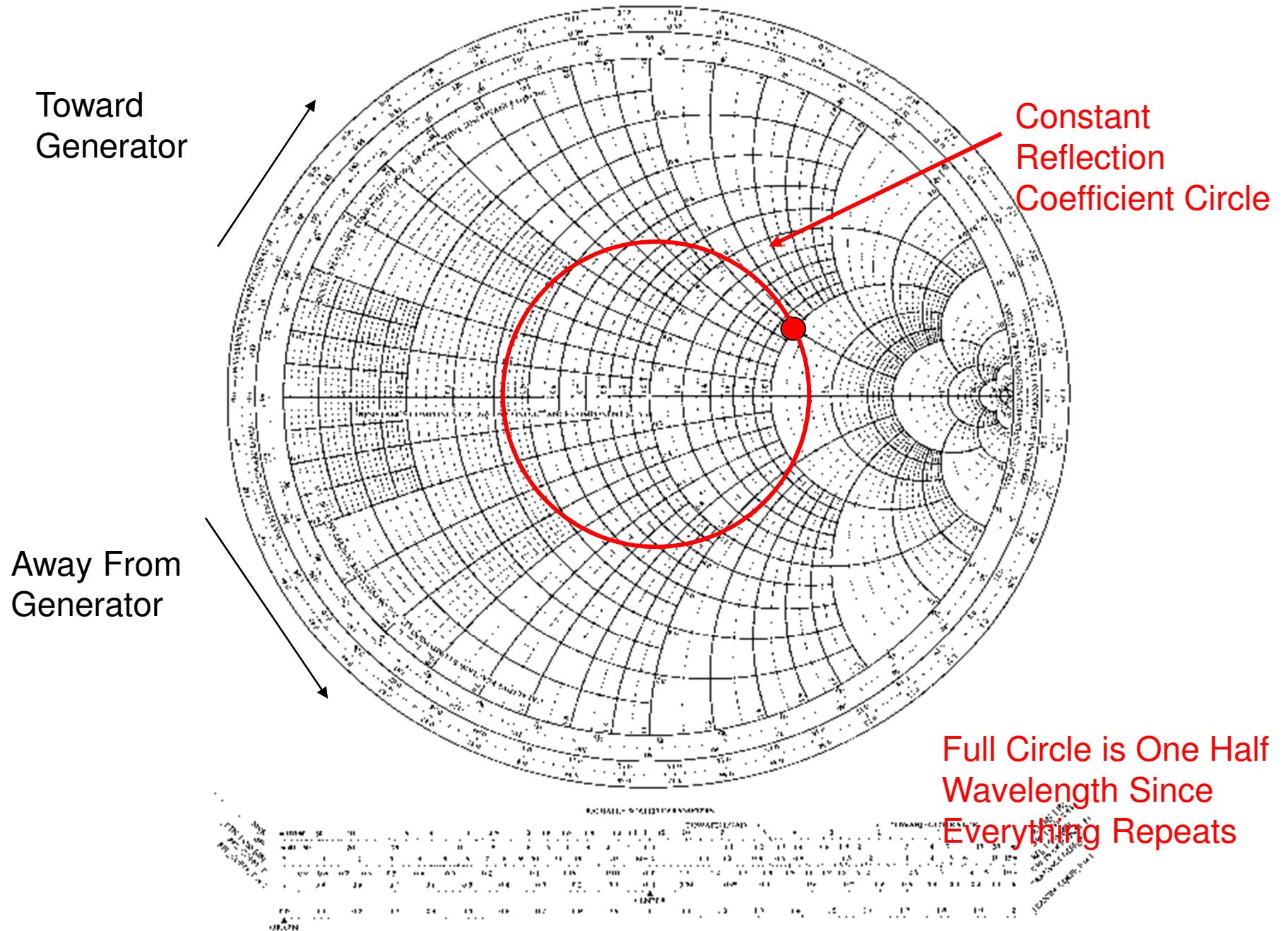


Complex Admittance

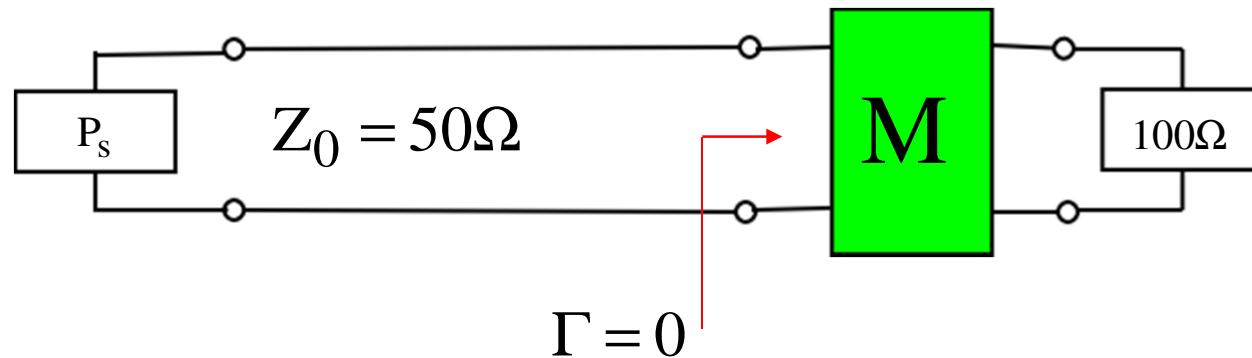


Matching

- For a matching network that contains elements connected in series and parallel, we will need two types of Smith charts
 - impedance Smith chart
 - admittance Smith Chart
- The admittance Smith chart is the impedance Smith chart rotated 180 degrees.
 - We could use one Smith chart and flip the reflection coefficient vector 180 degrees when switching between a series configuration to a parallel configuration.



Matching Example

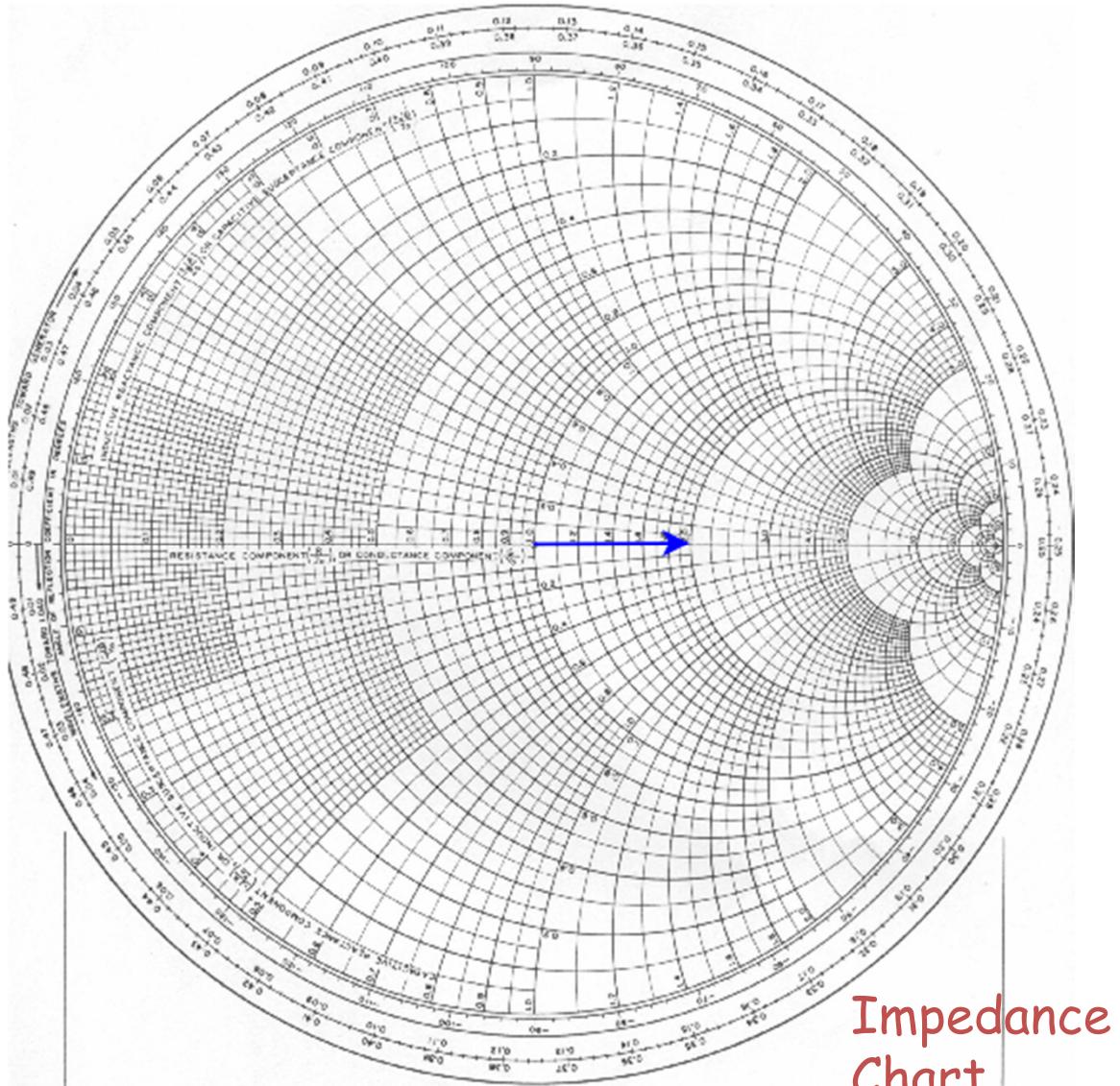


Match 100Ω load to a 50Ω system at 100MHz

A 100Ω resistor in parallel would do the trick but $\frac{1}{2}$ of the power would be dissipated in the matching network. We want to use only lossless elements such as inductors and capacitors so we don't dissipate any power in the matching network

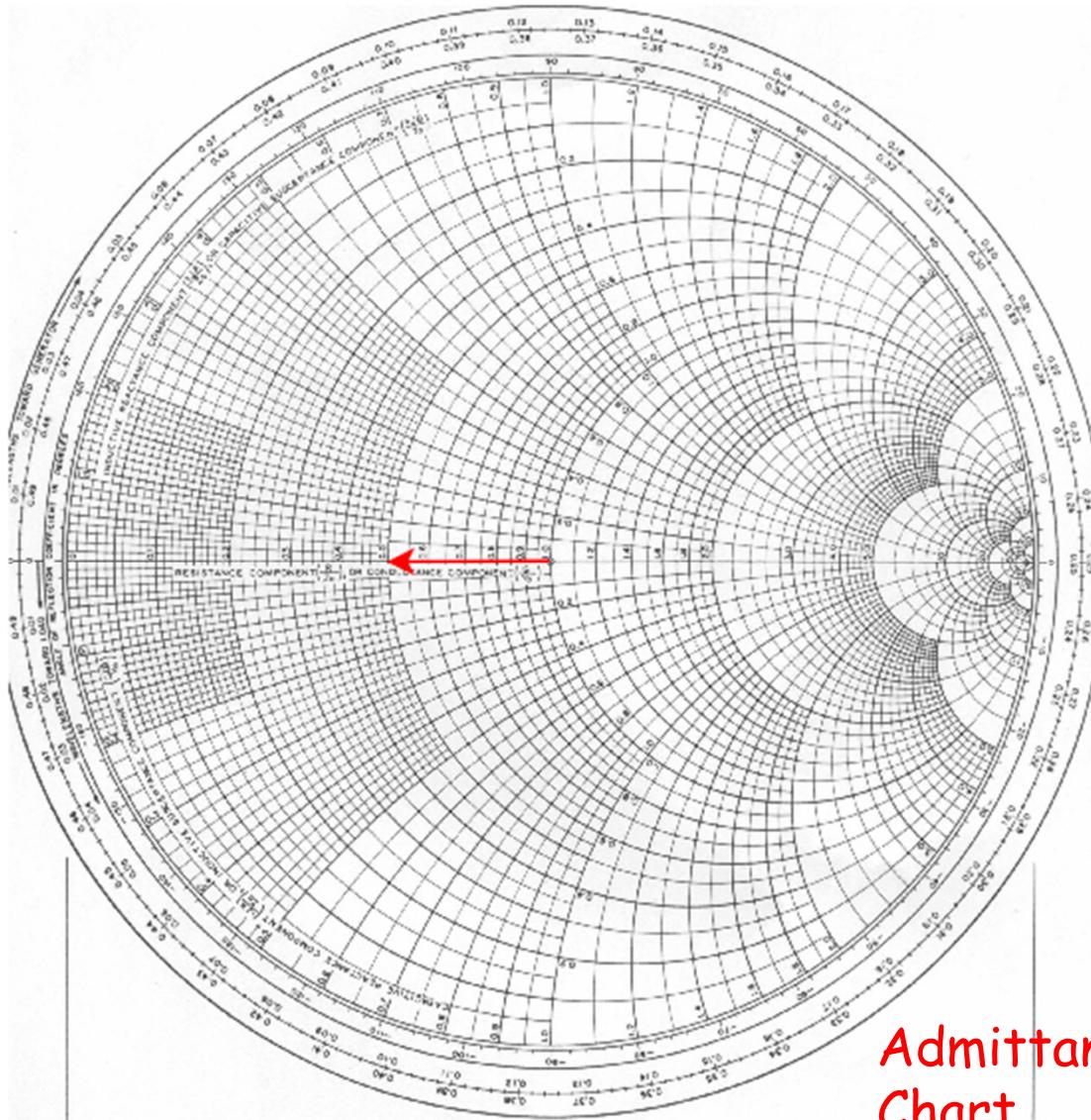
Matching Example

- We need to go from $z=2+j0$ to $z=1+j0$ on the Smith chart
- We won't get any closer by adding series impedance so we will need to add something in parallel.
- We need to flip over to the admittance chart



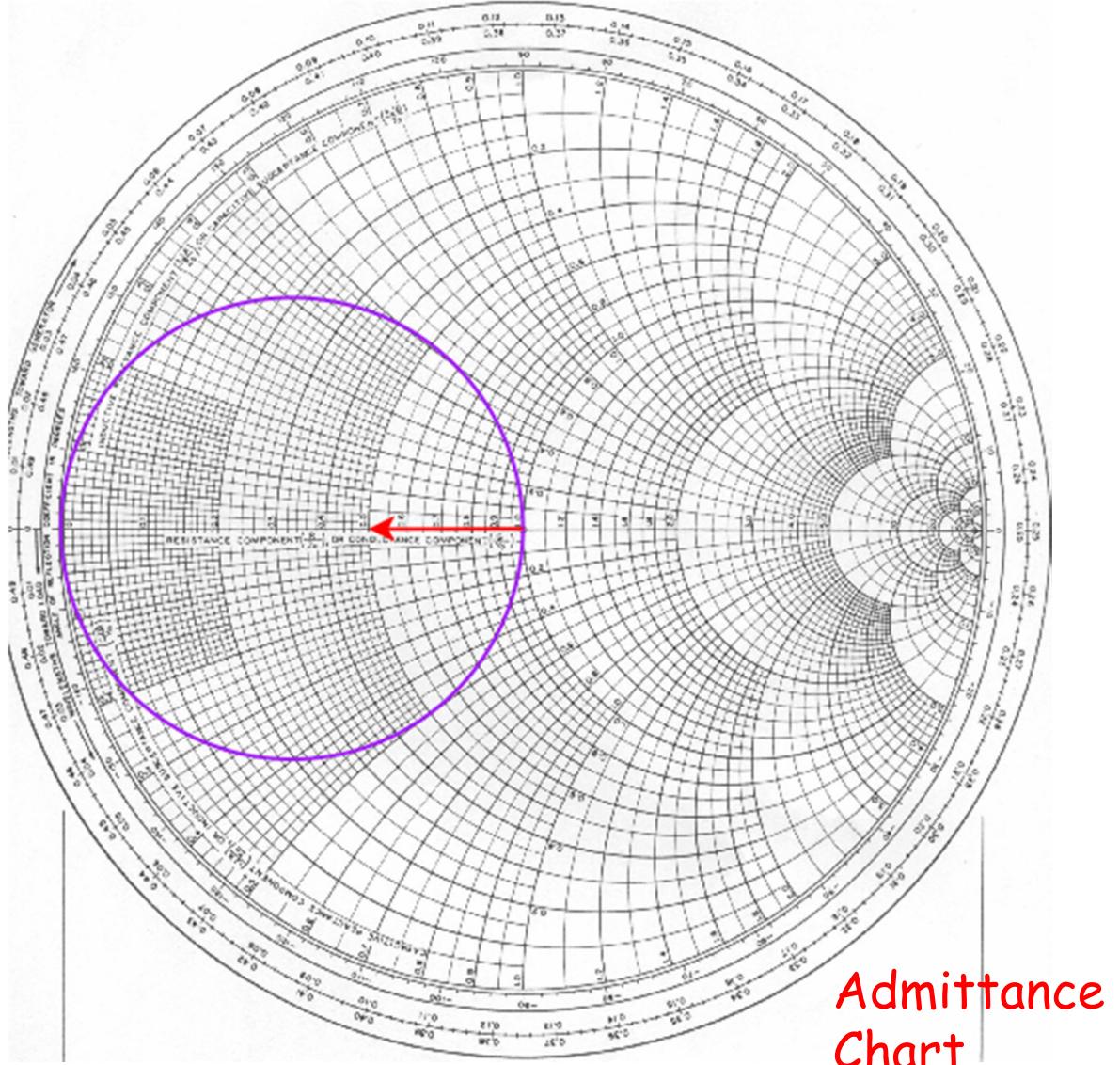
Matching Example

- $y=0.5+j0$
- Before we add the admittance, add a mirror of the $r=1$ circle as a guide.



Matching Example

- $y=0.5+j0$
- Before we add the admittance, add a mirror of the $r=1$ circle as a guide
- Now add positive imaginary admittance.



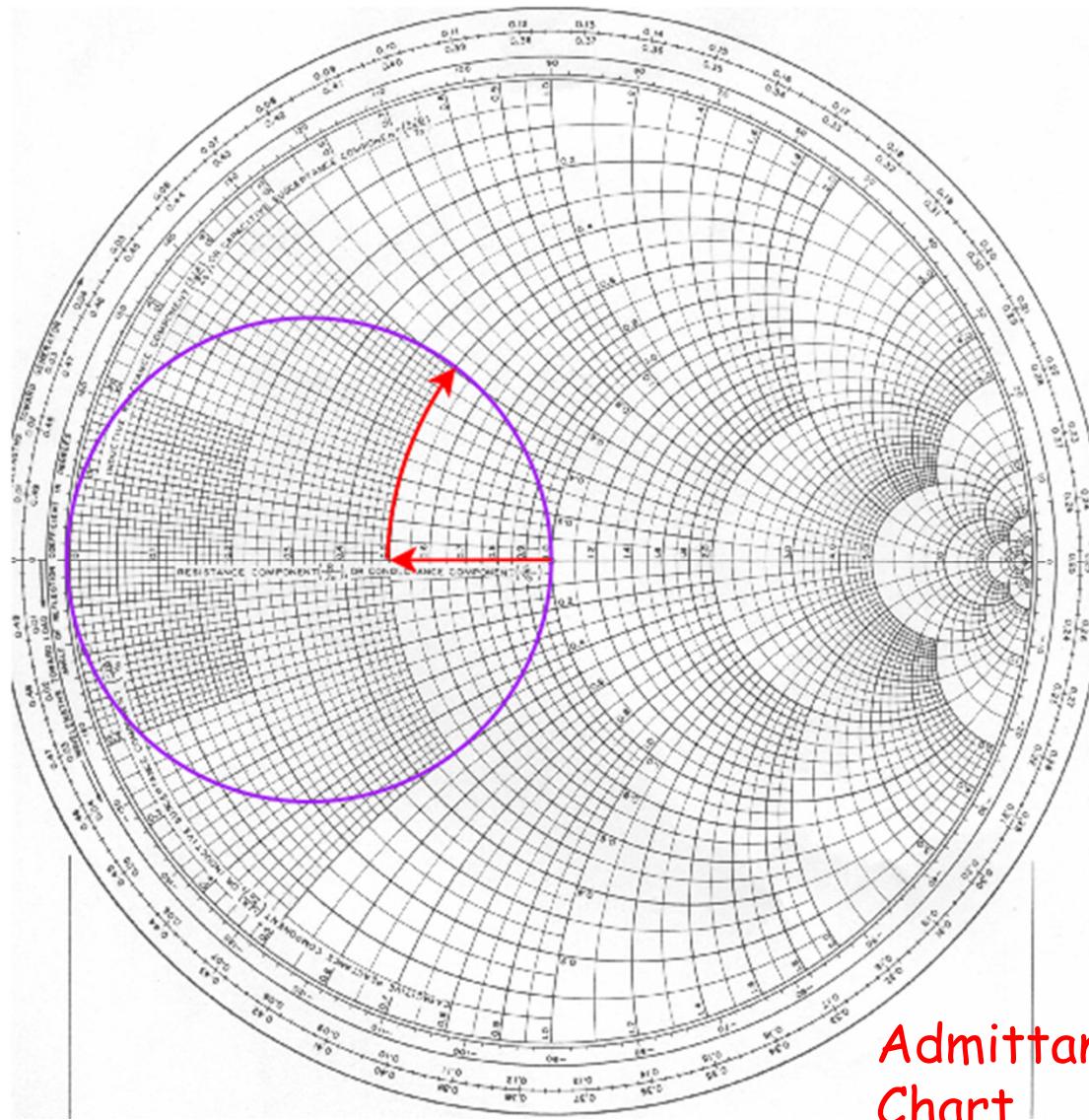
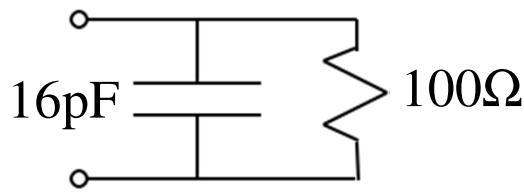
Matching Example

- $y=0.5+j0$
- Before we add the admittance, add a mirror of the $r=1$ circle as a guide
- Now add positive imaginary admittance $j_b = j0.5$

$$j_b = j0.5$$

$$\frac{j0.5}{50\Omega} = j2\pi(100\text{MHz})C$$

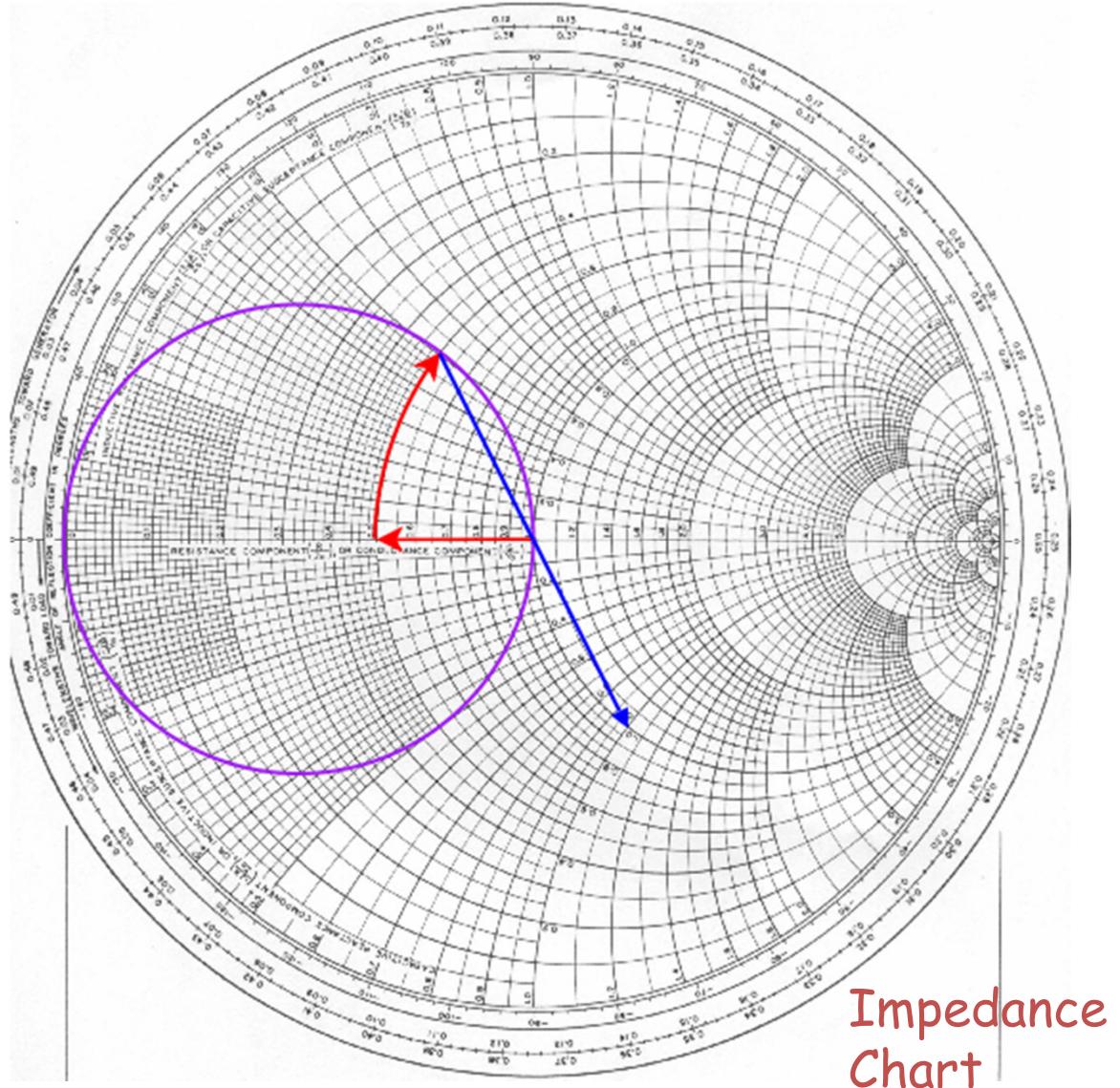
$$C = 16\text{pF}$$



Admittance
Chart

Matching Example

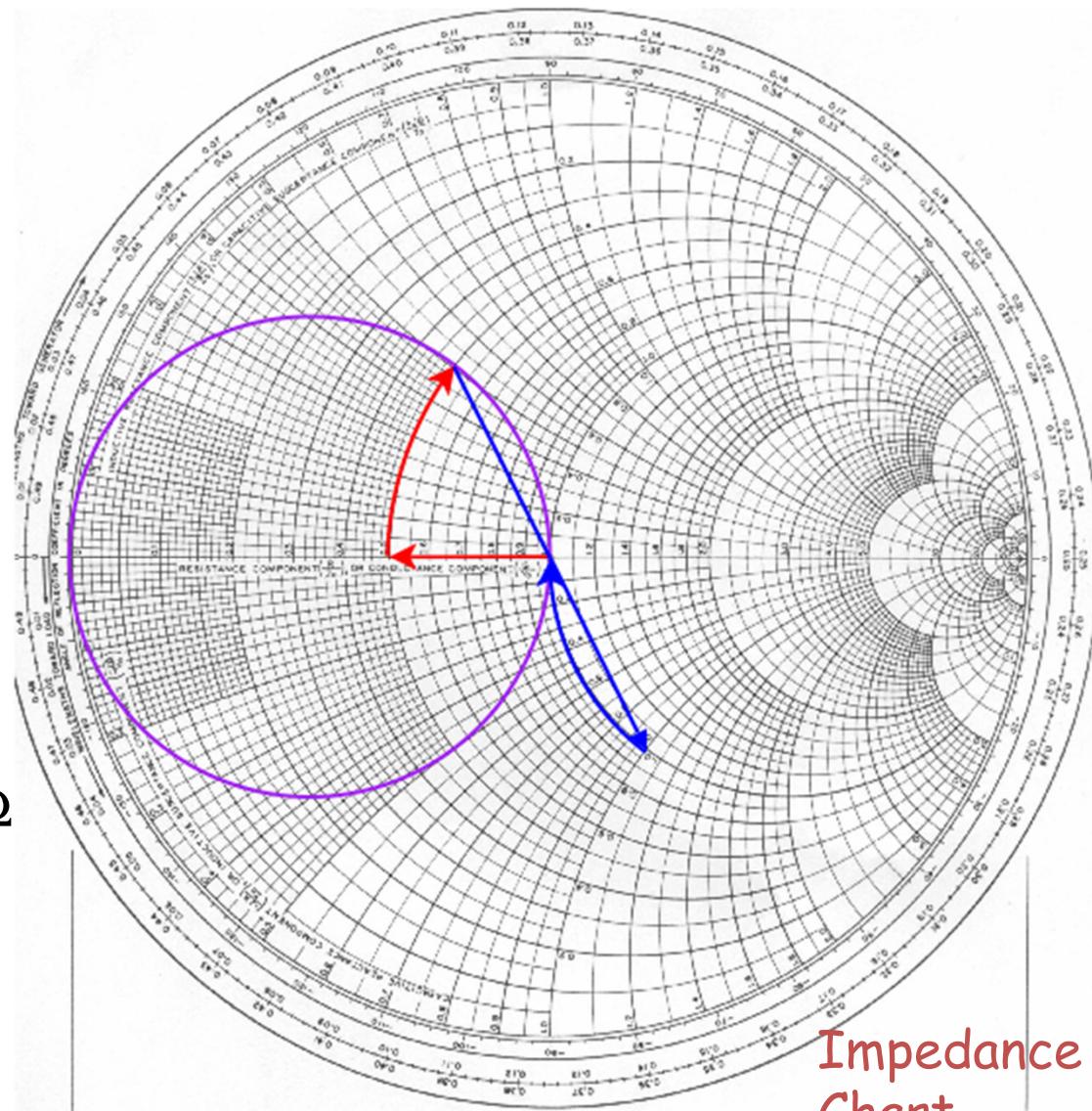
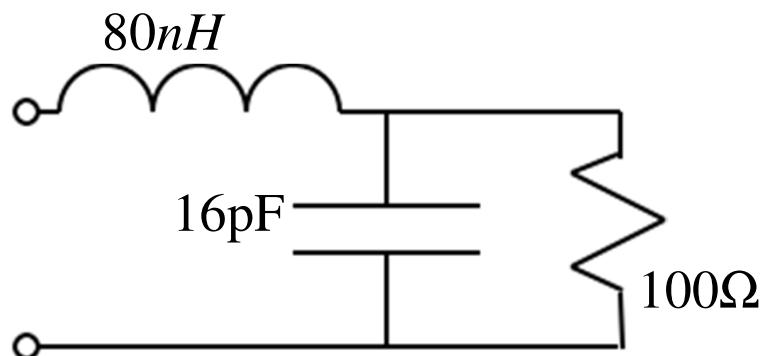
- We will now add series impedance
- Flip to the impedance Smith Chart
- We land at on the $r=1$ circle at $x=-1$



Matching Example

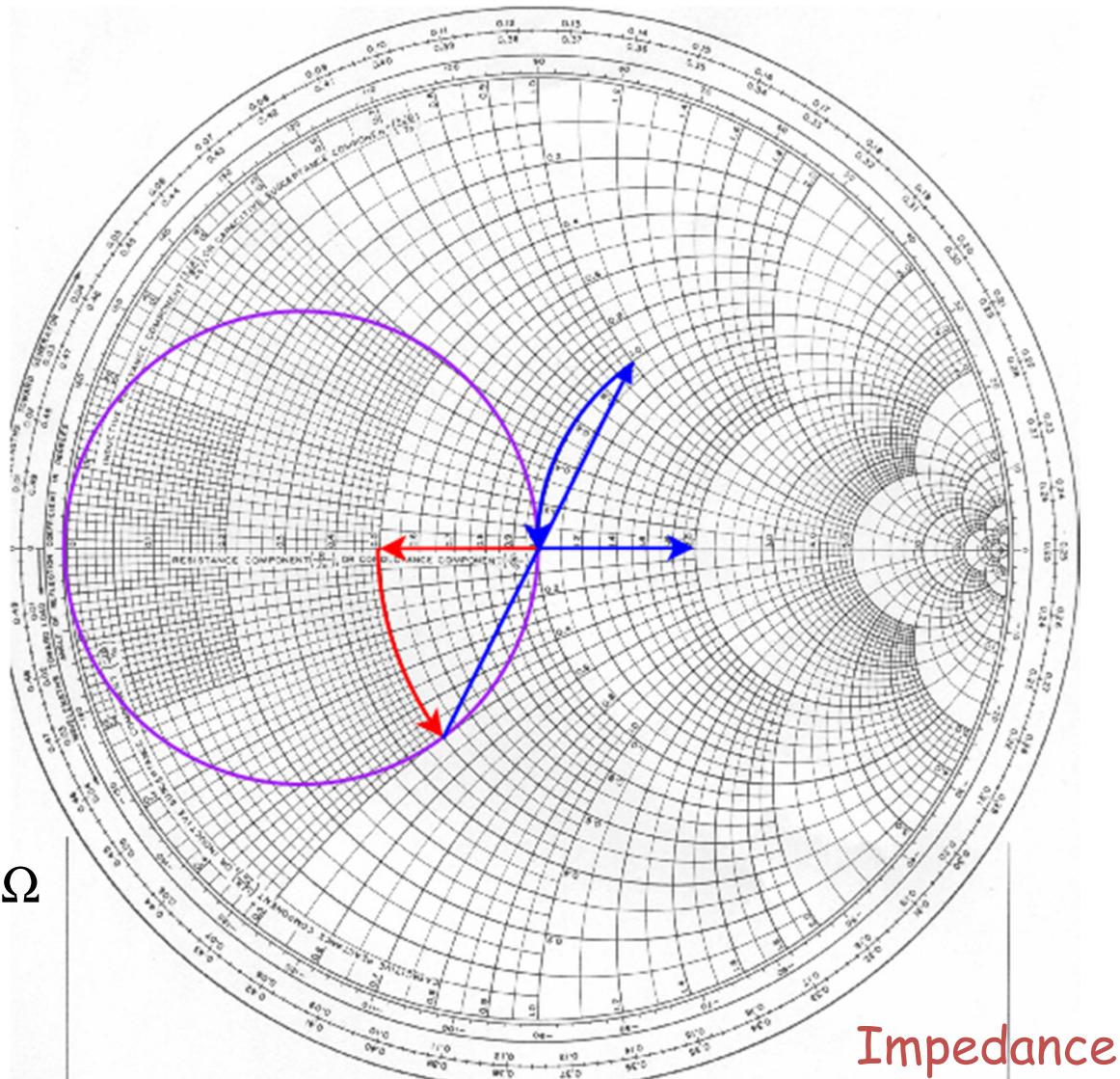
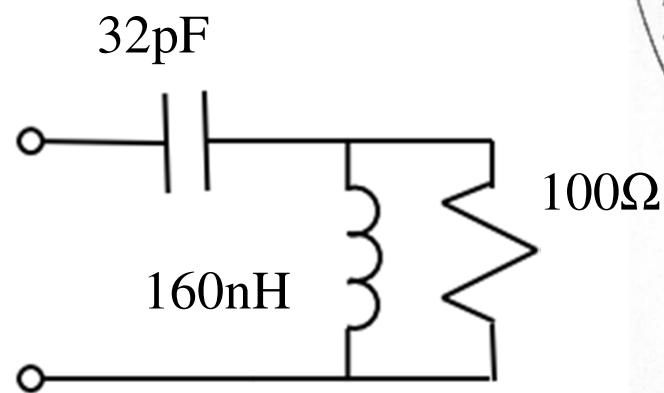
- Add positive imaginary admittance to get to $z=1+j0$
 $jx = j1.0$

$$(j1.0)50\Omega = j2\pi(100\text{MHz})L$$
$$L = 80\text{nH}$$



Matching Example

- This solution would have also worked



Mainstream vs. RF Electronics

Mainstream electronics

Microprocessors, memories, consumer electronics

Transistor types

- Bipolar: BJT (few Applications)
 - FET: MOSFET (Standard)
-

Semiconductors

- Si

RF Electronics

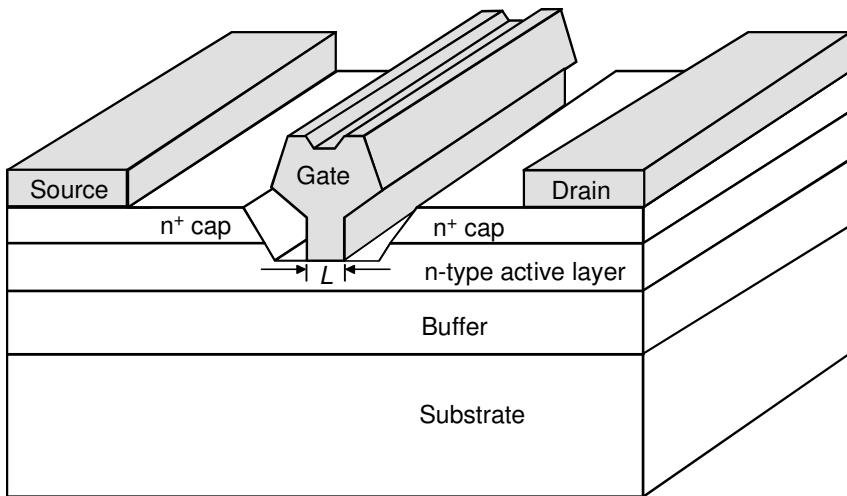
(HF, GHz, microwave electronics)

Transistor types

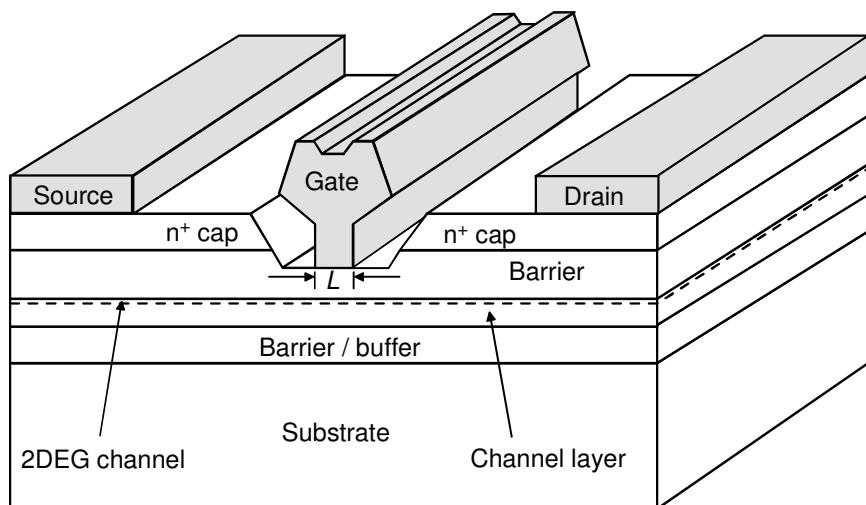
- Bipolar
 - HBT (Heterojunction Bipolar Transistor)
 - BJT (Bipolar Junction Transistor)
- FET
 - MESFET (Metal Semiconductor FET)
 - HEMT (High Electron Mobility Transistor)
 - SIT (Static Induction Transistor)
 - MOSFET (Metal Oxide Semiconductor FET)

Semiconductors

- III-V's (GaAs, InP, AlGaAs, InGaAs, InAlAs, ...)
- Si
- SiGe
- Wide bandgap materials (SiC, GaN, AlGaN)



MESFET Metal-Semiconductor FET



HEMT
High Electron Mobility Transistor
Channel: twodimensional electron gas (2DEG) at the interface channel layer - barrier

E. Simulation Examples

- ❖ Example #1

This Example gives comparison of the device output characteristics of a single quantum-well structure when using drift-diffusion and energy balance models

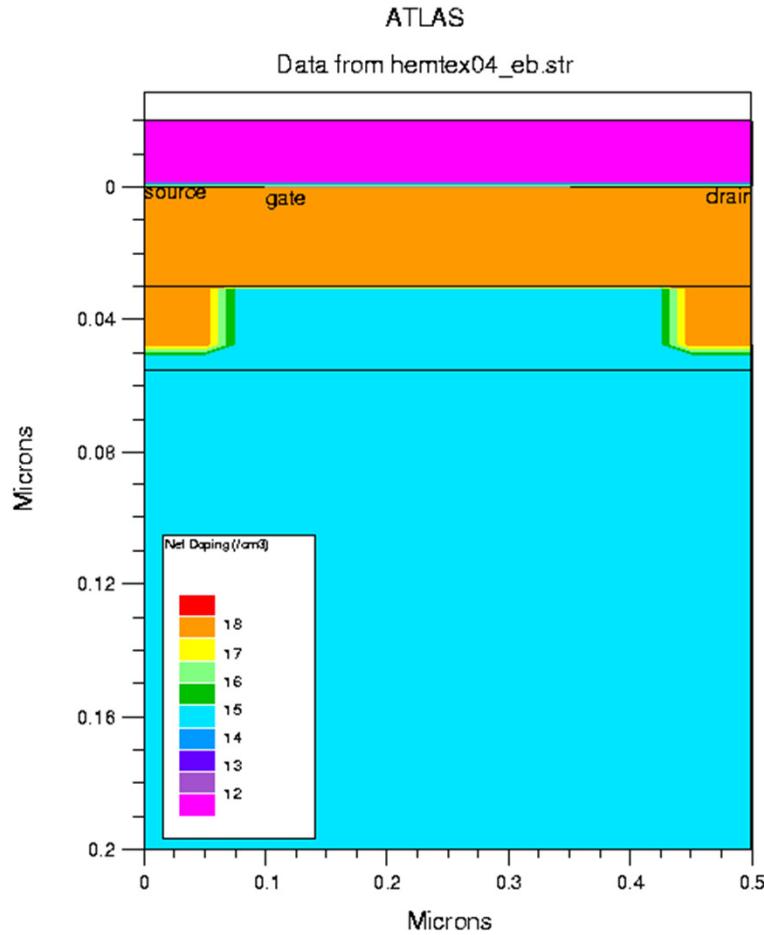
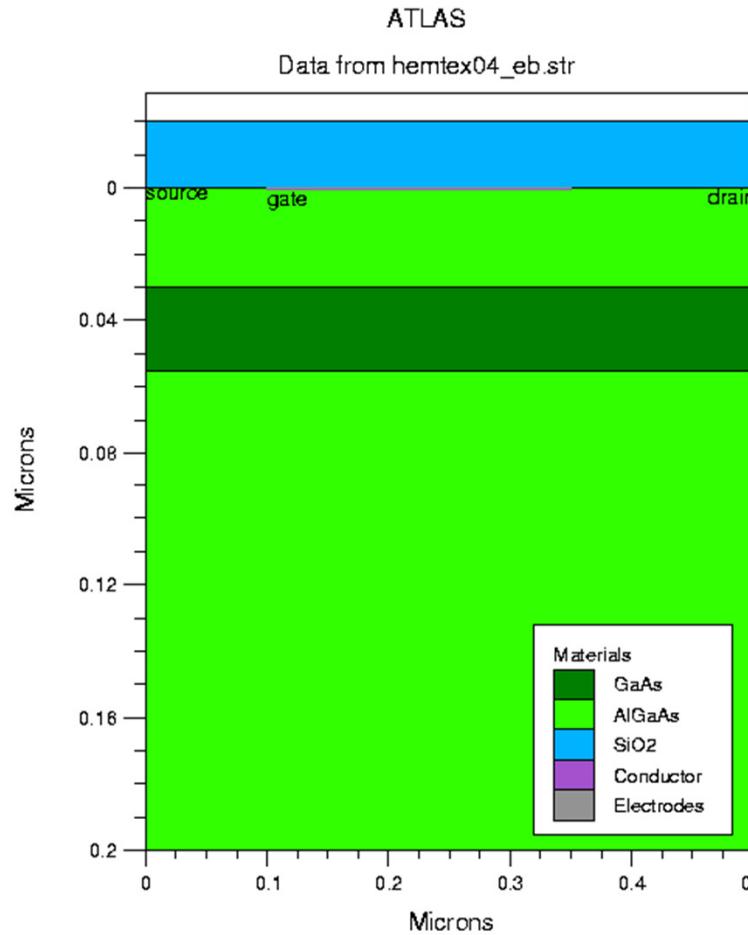
- ❖ Example #2

Simulation results of a pseudomorphic HEMT structure: device transfer and output characteristics with extraction of some significant device parameters, such as threshold voltage, maximum saturation current, etc.

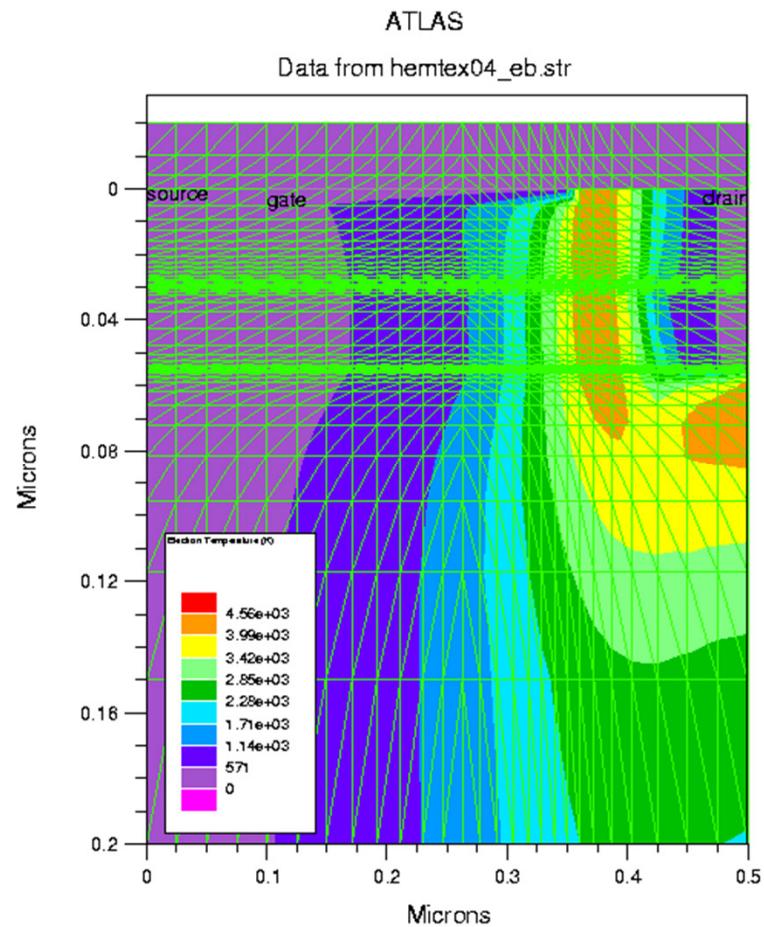
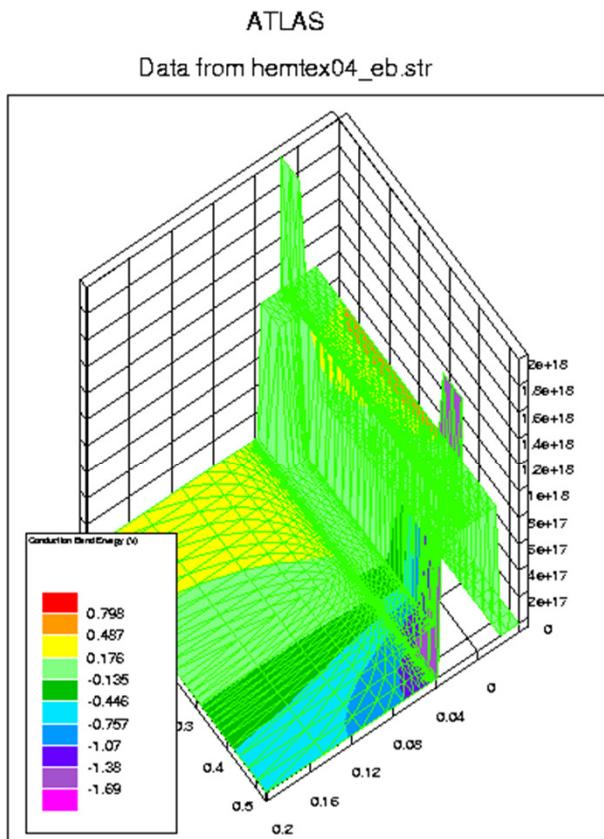
- ❖ Example #3

This is a follow-up of Example #2, in which AC analysis is performed and the device S-parameters calculated.

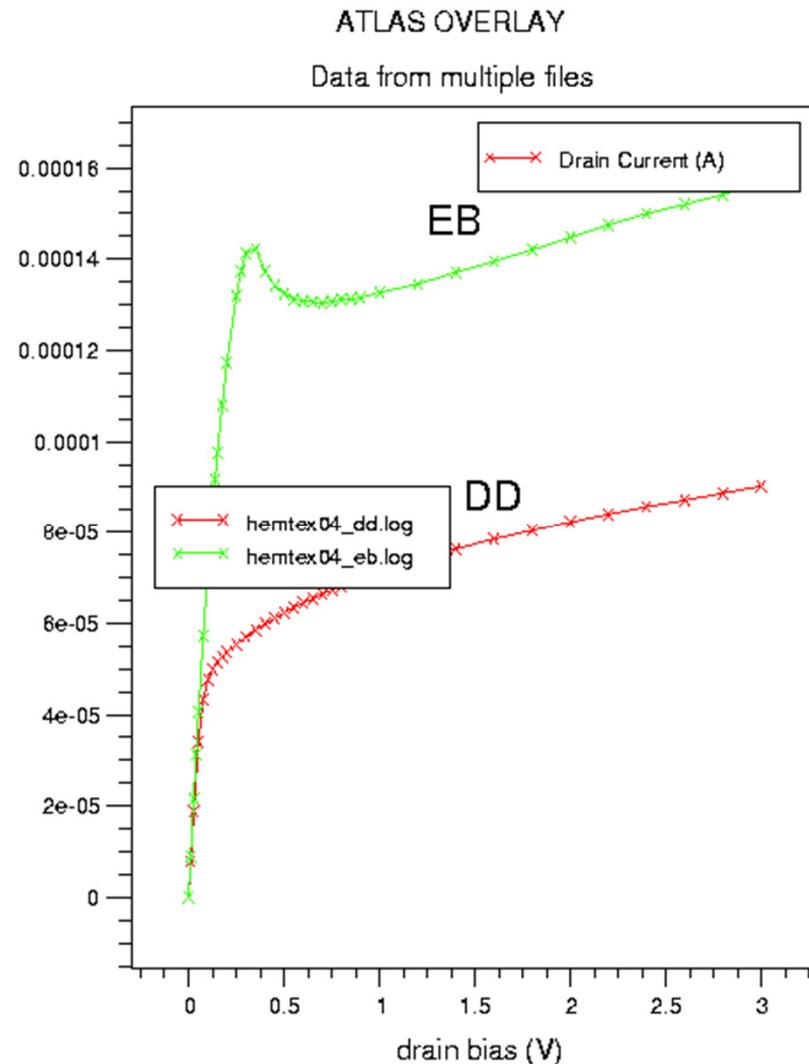
Example 1



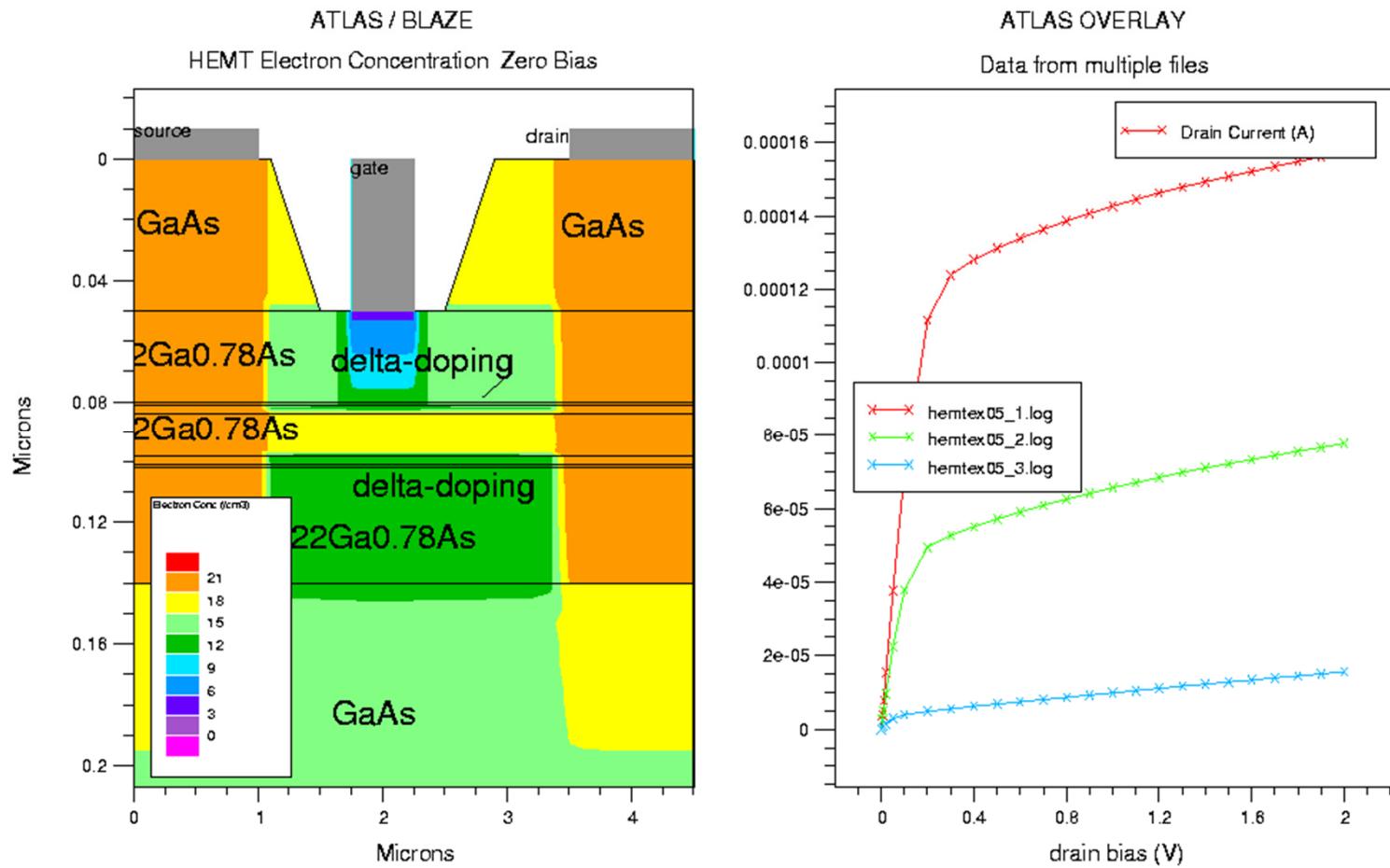
Example 1 (cont'd)



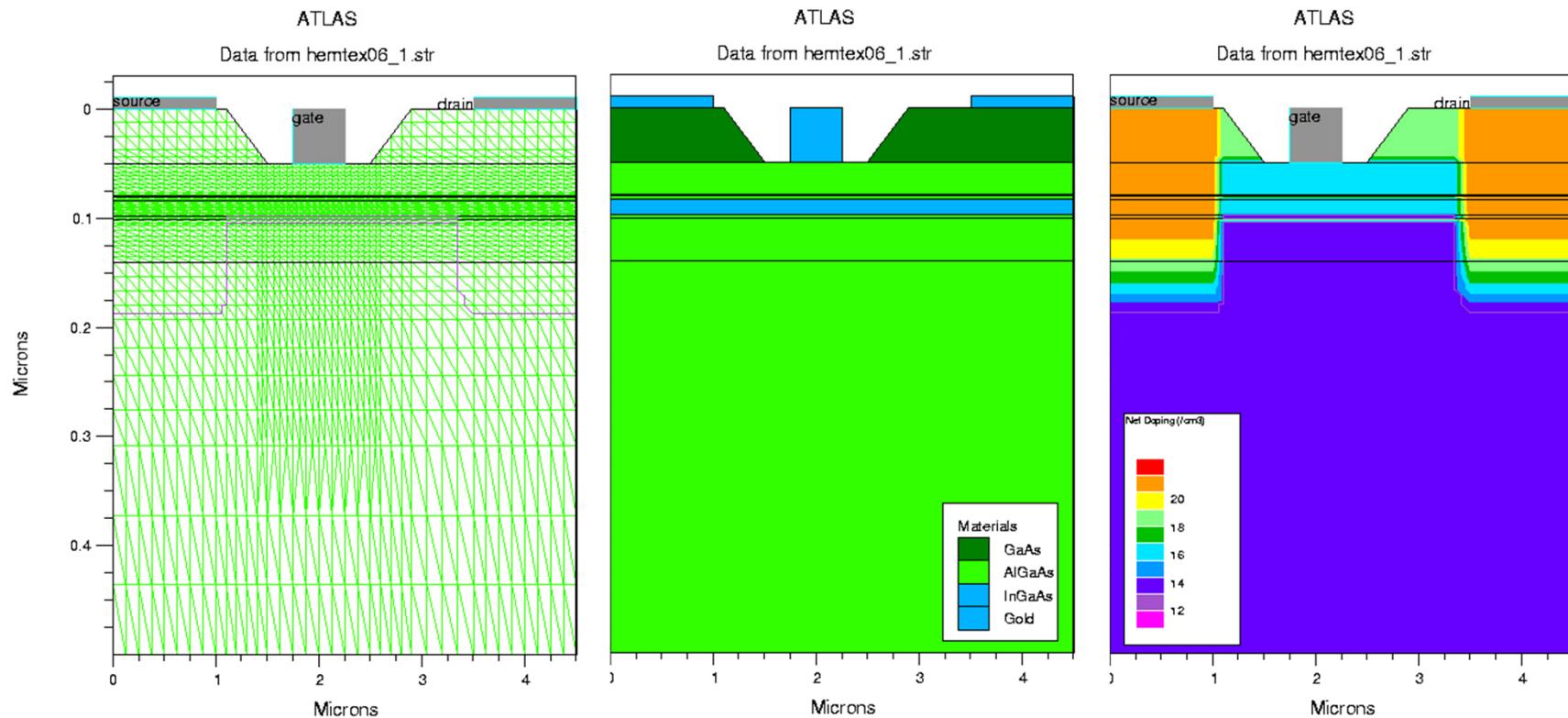
Example 1 (cont'd)



Example 2



Example 3



Example 3 (cont'd)

